



## Bill of materials

Table 1. X-NUCLEO-IKS5A1 bill of materials

Item	Q.ty	Ref.	Part / Value	Description	Manufacturer	Order code
1	13	C1, C2, C5, C6, C7, C8, C10, C12, C14, C15, C18, C19, C20	100nF		Yageo	CC0603KRX7R9BB104
2	6	C3, C4, C9, C11, C13, C17	10uF	Capacitor 10uF 0603	Kyocera AVX	0603ZD106KAT2A
3	1	C16	220nF		KEMET	C0603C224K3RACTU
4	1	CN5	Header 10x1		Samtec	ESQ-110-24-T-S
5	2	CN6, CN9	Header 8x1		Samtec	ESQ-108-24-T-S
6	1	CN8	Header 6x1		Samtec	ESQ-106-24-T-S
7	1	J1		Header 4x1	Adam Equipment	2PH1-04-UA
8	1	J2		No Description Available	Samtec	TMM-108-01-S-D
9	3	J4, J5, JP3		Header, 5-Pin, Dual row	Adam Equipment	2PH2-10-UA
10	1	J6	DIL24 Socket		Würth Electronics	61301211121
11	1	J8	Female connector		E-Tec	BL1-036-G-700-01
12	2	J7, J9		CONN HEADER VERT 12POS 1.27MM	Adam Equipment	HPH2-A-12-UA
13	1	JP1		Header, 17-Pin, Dual row	Panasonic	AXF5G3412A
14	1	JP2	Header 2x1	Jumper + Shunt	Würth Electronics	62000211121
15	2	JP4, JP5		Header, 4-Pin, Dual row	Adam Equipment	2PH2-08-UA
16	5	JP6, JP7, JP8, JP9, JP10	Header	Header, 3-Pin, shunt	Adam Equipment	2PH1-03-UA
17	13	R1, R2, R5, R6, R7, R8, R9, R10, R11, R12, R13, R14, R15	4k7		Yageo	RC0603FR-074K7L
18	1	R3	15k		Multicomp	MC0063W0603515K
19	1	R4	12k		Multicomp	MC0063W0603512K
20	2	R16, R17	2k2		Vishay	CRCW06032K20FKEA
21	3	R18, R20, R21	0R	RESISTOR, 0R0, 62.5mW, 1%, 0603	Yageo	AC0603FR-070RL
22	27	SB1, SB2, SB4, SB5, SB6, SB8, SB9, SB10, SB11, SB12, SB13, SB16, SB17, SB18, SB22,	Solder Bridge		Yageo	AC0603FR-070RL

Item	Q.ty	Ref.	Part / Value	Description	Manufacturer	Order code
		SB23, SB24, SB25, SB28, SB30, SB32, SB33, SB36, SB37, SB39, SB40, SB41				
23	1	SB20	Solder Bridge		Yageo	AC0603FR-070RL
24	1	SB26	Solder Bridge		Yageo	AC0603FR-070RL
25	1	U1	LDK130M-R, SOT23-5L	ULTRA LOW DROP LOW NOISE BICMOS VOLTAGE REGULATOR 1.8V	ST	<a href="#">LDK130M-R</a>
26	1	U2	NXS0108BQX	Level Shift	Nexperia	NXS0108BQX
27	1	U3	NXS0104BQX		Nexperia	NXS0104BQX
28	1	U4	ISM6HG256X	No Description Available	ST	<a href="#">ISM6HG256XTR</a>
29	1	U5	IIS2DULPX, LGA 12L 2.0x2.0x0.74 mm	2.0x2.0x0.7 12L	ST	<a href="#">IIS2DULPXTR</a>
30	1	U6	ILPS22QS, HLGA 2X2X.8 10L EXP. SILIC .91SQ	No Description Available	ST	<a href="#">ILPS22QSTR</a>
31	1	U7	IIS2MDC, LGA2X2X0.7 12 LEADS		ST	<a href="#">IIS2MDCTR</a>
32	1	U8	ISM330IS, LGA 14L 2.5x3x0.86 mm	2.5x3.0x0.83 14L	ST	<a href="#">ISM330ISTR</a>
33	21	JP3, JP4, JP5, JP6, JP8, JP9, JP10,J4,J5	2 MM SHUNT		Multicomp	MC-2205BG

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